intel

4004 SINGLE CHIP 4-BIT P-CHANNEL MICROPROCESSOR

- 4-Bit Parallel CPU With 46 Instructions
- Instruction Set Includes Conditional Branching, Jump to Subroutine and Indirect Fetching
- Binary and Decimal Arithmetic Modes
- 10.8 Microsecond Instruction Cycle

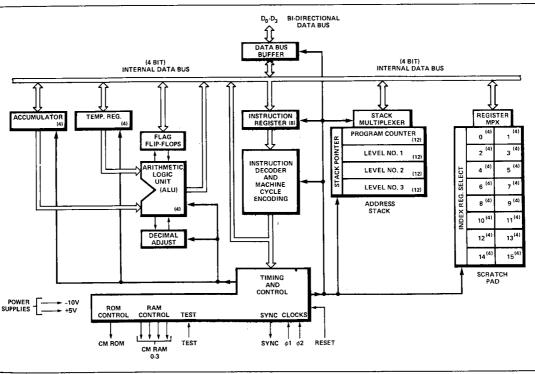
- CPU Directly Compatible With MCS-40 ROMs and RAMs
- Easy Expansion One CPU can Directly Drive up to 32,768 Bits of ROM and up to 5120 Bits of RAM
- Standard Operating Temperature Range of 0° to 70°C
- Also Available With -40° to +85°C Operating Range

The Intel® 4004 is a complete 4-bit parallel central processing unit (CPU). The 4004 easily interfaces with keyboards, switches, displays, A-D converters, printers and other peripheral equipment.

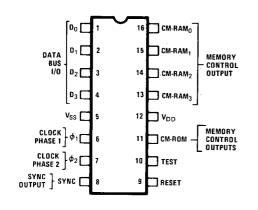
The CPU can directly address 4K 8-bit instruction words of program memory and 5120 bits of data storage RAM. Sixteen index registers are provided for temporary data storage. Up to 16 4-bit input ports and 16 4-bit output ports may also be directly addressed.

The 4004 is fabricated with P-channel silicon gate MOS technology.





Pin Description



D_0-D_3

BIDIRECTIONAL DATA BUS. All address and data communication between the processor and the RAM and ROM chips occurs on these 4 lines,



RESET

RESET input. A logic "1" level at this input clears all flags and status registers and forces the program counter to zero. To completely clear all address and index registers, RESET must be applied for 64 clock cycles (8 machine cycles).

TEST

TEST input. The logical state of this signal may be tested with the JCN instruction.

SYNC

SYNC output. Synchronization signal generated by the processor and set to the ROM and RAM chips. It indicates the beginning of an instruction cycle.

CM-ROM

CM-ROM output. This is the ROM selection signal sent out by the processor when data is required from program memory.

CM-RAM₀ - CM-RAM₃

CM-RAM outputs. These are the bank selection signals for the 4002 RAM chips in the system.

^φ1^{, φ}2

Two phase clock inputs.

V_{SS}

Most positive voltage.

V_{DD}

V_{SS} -15 ±5% main supply voltage.

Instruction Set Format

A. Machine Instructions

- 1 word instruction 8-bits requiring 8 clock periods (instruction cycle).
- 2 word instruction 16-bits requiring 16 clock periods (2 instruction cycles).

Each instruction is divided into two four-bit fields. The upper 4-bits is the OPR field containing the operation code. The lower 4-bits is the OPA field containing the modifier. For two word instructions, the second word contains address information or data.

The upper 4-bits (OPR) will always be fetched before the lower 4-bits (OPA) during $\rm M_1$ and $\rm M_2$ times respectively.

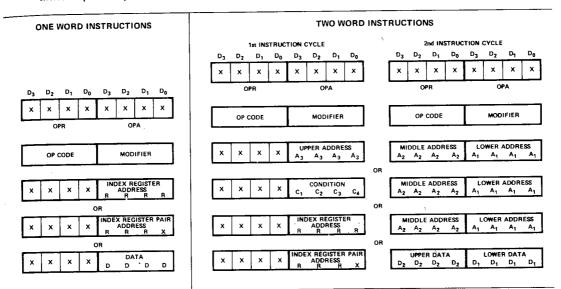


Table I. Machine Instruction Format

B. Input/Output and RAM Instructions and Accumulator Group Instructions

In these instructions (which are all single word) the OPR contains a 4-bit code which identifies either the I/O instruction or the accumulator group instruction and the OPA contains a 4-bit code which identifies the operation to be performed. Table II illustrates the contents of each 4-bit field.

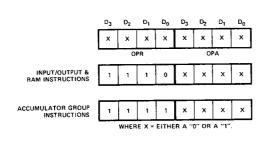


Table II. I/O and Accumulator Group Instruction Formats

4004 Instruction Set BASIC INSTRUCTIONS (* = 2 Word Instructions)

Hex Code	MNEMON	C D ₃ D ₂ D ₁ D ₀	OPA D ₃ D ₂ D ₁ D ₀	DESCRIPTION OF OPERATION				
00	NOP	0000	0 0 0 0	No operation.				
1 -	*JCN	0 0 0 1 A ₂ A ₂ A ₂ A ₂	C ₁ C ₂ C ₃ C ₄ A ₁ A ₁ A ₃ A ₁	Jump to ROM address A_2 A_2 A_2 A_2 A_3 A_4 A_5 A_4 (within the same ROM that contains this JCN instruction) if condition C_1 C_2 C_3 C_4 is true, otherwise go to the next instruction in sequence.				
2 -	* FIM	0 0 1 0 D ₂ D ₂ D ₂ D ₂	R R R 0 D, D, D, D,	Fetch immediate (direct) from ROM Data D $_2$ D $_2$ D $_2$ D $_2$ D $_3$ D $_4$ D $_4$ to index register pair location RRR.				
3 -	FIN	0 0 1 1	RRR 0	Fetch indirect from ROM. Send contents of index register pair location 0 out as an address. Data fetched is placed into register pair location RRR.				
3 -	JIN	0 0 1 1	RRR1	Jump indirect. Send contents of register pair RRR out as an address at A_1 and A_2 time in the instruction cycle.				
4 -	*JUN	0 1 0 0 A ₂ A ₂ A ₂ A ₂	$A_3 A_3 A_3 A_3 A_3 A_1 A_1 A_1 A_1 A_1 A_1$	Jump unconditional to ROM address A ₃ A ₃ A ₃ A ₃ A ₂ A ₂ A ₂ A ₂ A ₂ A ₄ A ₄ A ₅ A ₅ A ₆ A ₇				
5 -	*JMS	0 1 0 1 A ₂ A ₂ A ₂ A ₂	A ₃ A ₃ A ₃ A ₃ A ₁ A ₁ A ₁ A ₁	Jump to subroutine ROM address A ₃ A ₃ A ₃ A ₃ A ₄ A ₂ A ₂ A ₂ A ₂ A ₄ A ₄ A ₅ A ₅ A ₅ A ₆ A ₇				
6 -	INC	0 1 1 0	RRRR	Increment contents of register RRRR.				
7 -	*ISZ	0 1 1 1 A ₂ A ₂ A ₂ A ₂	R R R R A ₁ A ₁ A ₁	Increment contents of register RRRR. Go to ROM address $A_2 A_2 A_2 A_2 A_2 A_1 A_1 A_1 A_1 A_2$ (within the same ROM that contains this ISZ instruction) if result $\neq 0$, otherwise go to the next instruction in sequence.				
8 -	ADD	1 0 0 0	RRRR	Add contents of register RRRR to accumulator with carry.				
9 -	SUB	1 0 0 1	RRRR	Subtract contents of register RRRR to accumulator with borrow.				
A -	LD	1 0 1 0	RRRR	Load contents of register RRRR to accumulator.				
<u>B</u> -	XCH	1 0 1 1	RRRR	Exchange contents of index register RRRR and accumulator.				
C -	BBL	1100	DDDD	Branch back (down 1 level in stack) and load data DDDD to accumulator.				
D -	LDM	1 1 0 1	DDDD	Load data DDDD to accumulator.				
_F0	CLB	1111	0 0 0 0	Clear both. (Accumulator and carry)				
F1	CLC	1 1 1 1	0 0 0 1	Clear carry.				
F2	IAC	1111	0 0 1 0	Increment accumulator.				
_F3	CMC	1111	0 0 1 1	Complement carry.				
F4	CMA	1111	0 1 0 0	Complement accumulator.				
F5	RAL	1111	0 1 0 1	Rotate left. (Accumulator and carry)				
F6	RAR	1111	0 1 1 0	Rotate right. (Accumulator and carry)				
_F7	TCC	1111	0 1 1 1	Transmit carry to accumulator and clear carry.				
F8	DAC	1111	1000	Decrement accumulator.				
_F9	TCS	1111	1001	Transfer carry subtract and clear carry.				
FA	STC	1111	1 0 1 0	Set carry.				
FB	DAA	1 1 1 1	1 0 1 1	Decimal adjust accumulator.				
FC	KBP	1111	1 1 0 0	Keyboard process. Converts the contents of the accumulator from a one out of four code to a binary code.				
FD	DCL	1111	1 1 0 1	Designate command line.				



4001/4002/4008/4009/4289 INPUT/OUTPUT AND RAM INSTRUCTIONS

Hex Code	MNEMON	IC D	3 E	0P	A D	, D _o	D) P P 2 D	, D _o	DESCRIPTION OF OPERATION
2 -	SRC					0	A	R F	₹ F	₹ 1	Send register control. Send the address (contents of index register pair RRR) to ROM and RAM at X ₂ and X ₃ time in the instruction cycle.
EO	WRM	1		1	1	0	0) () (0	Write the contents of the accumulator into the previously selected RAM main memory character.
E1	WMP	1		1	1	0	0	() (1	Write the contents of the accumulator into the previously selected RAM output port. (Output Lines)
E2	WRR	1	1	1	1	0	0	() 1	0	Write the contents of the accumulator into the previously selected ROM output port. (I/O Lines)
E3	WPM	1	1	ſ 	1	0	0	0	1	1	Write the contents of the accumulator into the previously selected half byte of read/write program memory (used with 4008/4009 or 4289 only)
E4	WR0	. 1	1		1	0	0	1	0	0	Write the contents of the accumulator into the previously selected RAM status character 0.
E5	WR1	. 1	1		1	0	0	1	0	1	Write the contents of the accumulator into the previously selected RAM status character 1.
E6	WR2	1	1		1	0	0	1	1	0	Write the contents of the accumulator into the previously selected RAM status character 2.
E7	WR3	1	1		1	0	0	1	1	1	Write the contents of the accumulator into the previously selected RAM status character 3.
E8	SBM	1	1		1	0	1	0	0	0	Subtract the previously selected RAM main memory character from accumulator with borrow.
E9	RDM	1	1	1	ı	0	1	0	0	1	Read the previously selected RAM main memory character into the accumulator.
EA	RDR	1	1	1		0	1	0	1	0	Read the contents of the previously selected ROM input port into the accumulator. (I/O Lines)
EB	ADM	1	1	1		0	1	0	1	1	Add the previously selected RAM main memory character to accumulator with carry.
EC	RD0	1	1	1	_	0	1	1	0	0	Read the previously selected RAM status character 0 into accumulator.
ED	RD1	1	1	1		0	1	1	0	1	Read the previously selected RAM status character 1 into accumulator.
EE	RD2	1	1	1		0	1	1	1	0	Read the previously selected RAM status character 2 into accumulator.
EF	RD3	1	1	1		0	1	1	1	1	Read the previously selected RAM status character 3 into accumulator.



4004 Instruction Codes

Hex Mnemonic	Hex Mnemonic	Hex Mnemonic	Hex Mnemonic
00 -	40 JUN	80 ADD 0	CO BBL O
01 -	41 JUN	81 ADD 1	C1 BBL 1
02 -	42 JUN	82 ADD 2	C2 BBL 2
03 -	43 JUN	83 ADD 3	C3 BBL 3
04 -	44 JUN	84 ADD 4	C4 BBL 4
05 -	45 JUN	85 ADD 5	C5 BBL 5
06 -	46 JUN	86 ADD 6	C6 BBL 6
07 -	47 JUN	87 ADD 7	C7 BBL 7
08 -	48 JUN	88 ADD 8	C8 BBL 8
09 -	49 JUN	89 ADD 9	C9 BBL 9
0A -	4A JUN	8A ADD 10	CA BBL 10
0B —	4B JUN	8B ADD 11	CB BBL 11
0C -	4C JUN	8C ADD 12	CC BBL 12
0D -	4D JUN	8D ADD 13	CD BBL 13
0E -	4E JUN Second hex	8E ADD 14	CE BBL 14
0F —	4F JUN digit is part	8F ADD 15	CF BBL 15
10 JCN CN=0	50 JMS of jump	90 SUB 0	DO LDM O
11 JCN CN=1 also JNT	51 JMS address.	91 SUB 1	D1 LDM 1
12 JCN CN=2 also JC	52 JMS	92 SUB 2	D2 LDM 2
13 JCN CN=3	53 JMS	93 SUB 3	D3 LDM 3
14 JCN CN=4 also JZ	54 JMS	94 SUB 4	D4 LDM 4
15 JCN CN=5	55 JMS	95 SUB 5	D5 LDM 5
16 JCN CN=6	56 JMS	96 SUB 6	D6 LDM 6
17 JCN CN=7	57 JMS	97 SUB 7	D7 LDM 7
18 JCN CN=8	58 JMS	98 SUB 8	D8 LDM 8
19 JCN CN=9 also JT	59 JMS	99 SUB 9	D9 LDM 9
1A JCN CN=10 also JNC	5A JMS	9A SUB 10	DA LDM 10
18 JCN CN=11	5B JMS	9B SUB 11	DB LDM 11
1C JCN CN=12 also JNZ	5C JMS	9C SUB 12	DC LDM 12
1D JCN CN=13	5D JMS	9D SUB 13	DD LDM 13
1E JCN CN=14	5E JMS	9E SUB 14	DE LDM 14
1F JCN CN=15	5F JMS	9F SUB 15	DF LDM 15
20 FIM 0	60 INC $\overline{0}$	AO LD O	EO WRM
1 21 SRC 0	61 INC 1	A1 LD 1	E1 WMP
22 FIM 2	62 INC 2	A2 LD 2	E2 WRR
23 SRC 2	63 INC 3	A3 LD 3	E3 WPM
24 FIM 4	64 INC 4	A4 LD 4	E4 WRO
25 SRC 4	65 INC 5	A5 LD 5	E5 WR1
26 FIM 6	66 INC 6	A6 LD 6	E6 WR2
27 SRC 6	67 INC 7	A7 LD 7	E7 WR3
28 FIM 8	68 INC 8	A8 LD 8	E8 SBM
29 SRC 8	69 INC 9	A9 LD 9	E9 RDM
2A FIM 10	6A INC 10	AA LD 10	EA RDR
2B SRC 10	6B INC 11	AB LD 11	EB ADM
2C FIM 12	6C INC 12	AC LD 12	EC RDO
2D SRC 12 2E FIM 14	6D INC 13	AD LD 13	ED RD1
07 000 11	6E INC 14	AE LD 14	EE RD2
2F SRC 14 30 FIN 0	6F INC 15 70 ISZ 0	AF LD 15	EF RD3
31 JIN 0	70 ISZ 0 71 ISZ 1	BO XCH O	FO CLB
32 FIN 2	71 ISZ 1 72 ISZ 2	B1 XCH 1	F1 CLC
33 JIN 2	72 15Z Z 73 ISZ 3	B2 XCH 2 B3 XCH 3	F2 IAC
34 FIN 4	74 ISZ 4	B3 XCH 3 B4 XCH 4	F3 CMC F4 CMA
35 JIN 4	75 ISZ 5	B5 XCH 5	F5 RAL
36 FIN 6	76 ISZ 6	B6 XCH 6	F6 RAR
37 JIN 6	70 132 0 77 ISZ 7	B7 XCH 7	F7 TCC
38 FIN 8	78 ISZ 8	B8 XCH 8	F8 DAC
39 JIN 8	79 ISZ 9	B9 XCH 9	F9 TCS
3A FIN 10	7A ISZ 10	BA XCH 10	FA STC
3B JIN 10	7B ISZ 11	BB XCH 11	FB DAA
3C FIN 12	70 ISZ 12	BC XCH 12	FC KBP
3D JIN 12	7D ISZ 13	BD XCH 13	FD DCL
3E FIN 14	7E ISZ 14	BE XCH 14	FE -
3F JIN 14	7F ISZ 15	BF XCH 15	FF -
		7011 10	



Absolute Maximum Ratings*

Ambient Temperature Under Bias	0°C to 70°C
Storage Temperature	-55°C to + 125°C
L Valtages and Supply Voltage	
with respect to Vss	+0.5V to -20V
Power Dissipation	1.0 Watt
Power Dissipation	

*COMMENT:

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

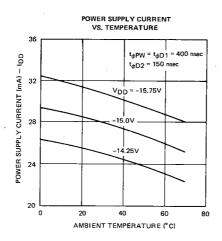
D.C. and Operating Characteristics

 $T_A = 0^{\circ} \text{C}$ to 70°C ; $V_{SS} - V_{DD} = 15 \text{V} \pm 5\%$; $t_{\phi PW} = t_{\phi D1} = 400$ nsec; logic "0" is defined as the more positive voltage (V_{IH}, V_{OH}); logic "1" is defined as the more negative voltage (V_{IL}, V_{OL}); Unless Otherwise Specified.

Symbol	Parameter	Min.	Limit Typ.	Max.	Unit	Test Conditions
lpp	Average Supply Current		30	40	mA	T _A =25°C
	IARACTERISTICS					
ILI	Input Leakage Current			10	μΑ	V _{IL} =V _{DD}
V _{IH}	Input High Voltage (Except Clocks)	V _{SS} -1.5		V _{SS} +.3	٧	
V _{IL}	Input Low Voltage (Except Clocks)	V _{DD}		V _{SS} -5.5	>	
V _{ILO}	Input Low Voltage	V _{DD}		V _{SS} -4.2	V	4004 TEST Input
V _{IHC}	Input High Voltage Clocks	V _{SS} -1.5		V _{SS} +.3	٧	
VILC	Input Low Voltage Clocks	V_{DD}		V _{SS} -13.4	V	
UTPUT	CHARACTERISTICS					
lLO	Data Bus Output Leakage Current			10	μΑ	V _{OUT} =-12V
V _{OH}	Output High Voltage	V _{SS} 5V	Vss		V	Capacitance Load
рг	Data Lines Sinking Current	8	15		mA	V _{OUT} =V _{SS}
loL	CM-ROM Sinking Current	6.5	12		mA	V _{OUT} =V _{SS}
loL	CM-RAM Sinking Current	2.5	.6		mΑ	V _{OUT} =V _{SS}
VoL	Output Low Voltage, Data Bus, CM, SYNC	V _{SS} -12		V _{SS} -6.5	٧	l _{OL} =0.5mA
RoH	Output Resistance, Data Line "0" Level		150	250	Ω	V _{OUT} =V _{SS} 5V
R _{OH}	CM-ROM Output Resistance, Data Line "0" Level		320	600	Ω	V _{OUT} =V _{SS} 5V
R _{OH}	CM-RAM Output Resistance, Data Line "0" Level		1.1	1.8	kΩ	V _{OUT} =V _{SS} 5V
CAPACIT	ANCE					<u> </u>
C _{\phi}	Clock Capacitance		14	20	pF	V _{IN} =V _{SS}
C _{DB}	Data Bus Capacitance		7	10	рF	V _{IN} =V _{SS}
C _{IN}	Input Capacitance			10	рF	V _{IN} =V _{SS}
Cour	Output Capacitance			. 10	pF	V _{IN} =V _{SS}



Typical D.C. Characteristics



A.C. Characteristics

 $T_A = 0^{\circ} C$ to $70^{\circ} C$, $V_{SS} - V_{DD} = 15 V \pm 5\%$



Symbol	Parameter	Min.	Limit Typ.	Max.	Unit	Test Conditions	
t _{CY}	Clock Period	1.35		2.0	μsec		
t _Ø R	Clock Rise Time			50	ns		
$t_{\phi F}$	Clock Fall Times			50	ns		
t _{øPW}	Clock Width	380		480	ns	· <u>·</u>	
t _{φD1}	Clock Delay ϕ_1 to ϕ_2	400		550	ns		
$t_{\phi D2}$	Clock Delay ϕ_2 to ϕ_1	150			ns		
t _W	Data-In, CM, SYNC Write Time	350	100		ns		
t _H [1,3]	Data-In, CM, SYNC Hold Time	40	20		ns		
t _H [3]	Data Bus Hold Time During M_2 - X_1 and and X_2 - X_3 Transition.	150			ns		
tos ^[2]	Set Time (Reference)	0			ns		
^t ACC	Data-Out Access Time Data Lines Data Lines SYNC CM-ROM CM-RAM			930 700 930 930 930	ns ns ns ns	C _{OUT} = 500pF Data Lines 200pF Data Lines ^[4] 500pF SYNC 160pF CM-ROM 50pF CM-RAM	
tон	Data-Out Hold Time	50	150	330	ns	C _{OUT} =20pF	

Notes: 1. t_H measured with t_{φR} = 10nsec.
 2. T_{ACC} is Data Bus, SYNC and CM-line output access time referred to the φ₂ trailing edge which clocks these lines out. tos is the same output access time referred to the leading edge of the next φ₂ clock pulse.
 3. All MCS-40 components which may transmit instruction or data to the 4004 at M₂ and X₂ always enter a float state until the

⁴⁰⁰⁴ takes over the data bus at X_1 and X_3 time. Therefore the t_H requirement is always insured since each component contributes $10\mu A$ of leakage current and 10pF of capacitance which guarantees that the data bus cannot change faster than $1V/\mu s$.

^{4.} CDATA BUS = 200pF if 4008 and 4009 or 4289 is used.

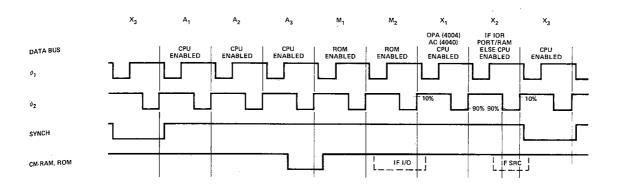


Figure 1. Timing Diagram.

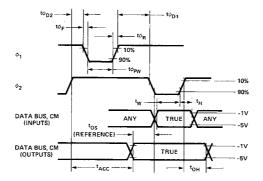




Figure 2. Timing Detail.